



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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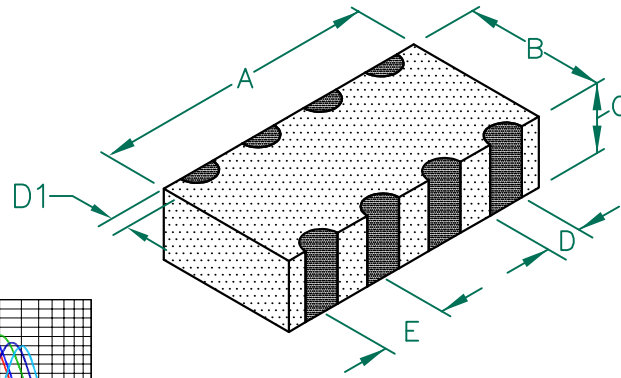


PHYSICAL DIMENSIONS:

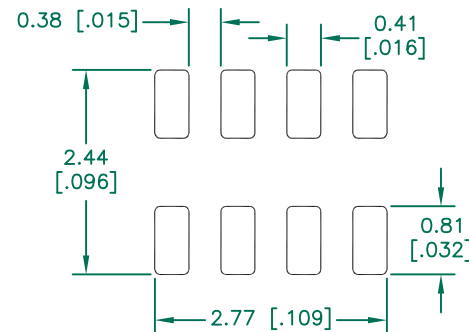
A	3.20 [.126]	± 0.20 [.008]
B	1.60 [.063]	± 0.20 [.008]
C	0.80 [.031]	± 0.20 [.008]
D	0.40 [.016]	± 0.15 [.006]
D1	0.30 [.012]	± 0.20 [.008]
E	0.80 [.031]	± 0.10 [.004]

DA1206B601R-10

UNCONTROLLED DOCUMENT



LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 (0.030) to this dimension)

ELECTRICAL CHARACTERISTICS:

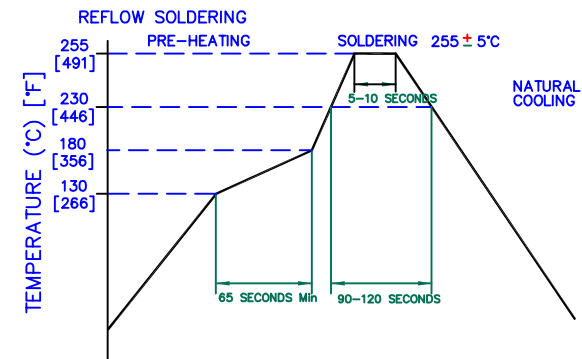
Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	600	
Minimum	450	
Maximum	750	200 mA

LINE TO LINE INSULATION RESISTANCE
>100 M Ω AT 75 VOLTS.

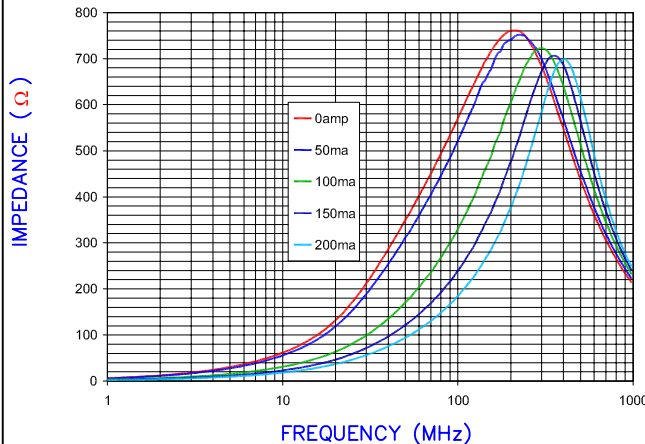
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL EMBOSSED PLASTIC TAPE.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMPERATURE TEMP: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (INCLUDING SELF-HEATING)

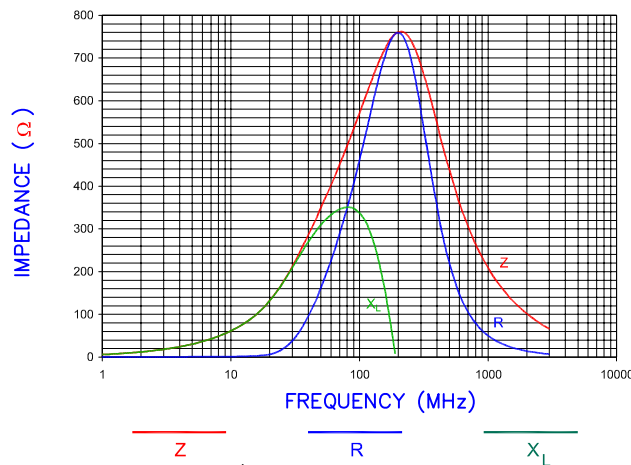
RECOMMENDED SOLDERING CONDITIONS



Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



|Z|, R, AND X vs. FREQUENCY



DIMENSIONS ARE IN mm [INCHES].		This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.		Laird	
E	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU		
D	UPDATE COMPANY LOGO	05/20/09	JRK	PROJECT/PART NUMBER:	REV
C	D1 dim chgd from 0.008 \pm 0.004 to 0.012 \pm 0.008. UPDATE COMPANY LOGO	10/30/07	JRK	DA1206B601R-10	E
B	CHANGE DCR, MODIFY NOTE 1 ADD ROHS	11/30/06	JRK	DATE:	SCALE: NTS
A	ORIGINAL DRAFT	03/30/04	TMB	03/30/04	SHEET:
REV	DESCRIPTION	DATE	INT	CAD # DA1206B601R-10-E	TOOL # -
				SHEET: 2 of 2	

